Title (en)

DICING DEVICE AND DICING METHOD

Title (de)

ZERTEILUNGSVORRICHTUNG UND ZERTEILUNGSVERFAHREN

Title (fr)

DISPOSITIF ET PROCÉDÉ DE DÉCOUPAGE EN DÉS

Publication

EP 2879164 A4 20151125 (EN)

Application

EP 13803775 A 20130614

Priority

- JP 2012136060 A 20120615
- JP 2013066501 W 20130614

Abstract (en)

[origin: US2015099428A1] To stably perform cutting process even on a workpiece formed from a brittle material, in a ductile mode with high precision, without causing cracking and/or breaking in the workpiece. A dicing device which performs cutting process on a workpiece includes: a dicing blade that is formed into a discoid shape from a diamond sintered body formed by sintering diamond abrasive grains, and contains 80% or more of the diamond abrasive grains; a spindle (rotating mechanism) configured to rotate the dicing blade; and a movement mechanism configured to move the workpiece relatively to the dicing blade while forming a constant cut depth on the workpiece by the dicing blade.

IPC 8 full level

H01L 21/301 (2006.01); **B24B 19/02** (2006.01); **B24B 27/06** (2006.01); **B24D 3/00** (2006.01); **B24D 3/06** (2006.01); **B24D 5/12** (2006.01); **B28D 5/00** (2006.01)

CPC (source: CN EP KR US)

B24B 9/065 (2013.01 - US); **B24B 19/02** (2013.01 - CN EP US); **B24B 27/06** (2013.01 - CN EP US); **B24D 3/00** (2013.01 - KR); **B24D 3/06** (2013.01 - KR); **B24D 5/12** (2013.01 - CN EP KR US); **B28D 5/0029** (2013.01 - EP US); **H01L 21/304** (2013.01 - KR); **H01L 21/78** (2013.01 - KR)

Citation (search report)

- [Y] WO 2008004365 A1 20080110 - TOKYO SEIMITSU CO LTD [JP], et al
- [YD] JP 2012030992 A 20120216 - MITSUBOSHI DIAMOND IND CO LTD
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Designated contracting state (EPC)

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US 201414569061 A 20141212; CN 201380031514 A 20130614; EP 13803775 A 20130614; JP 2013066501 W 20130614; JP 2014521434 A 20130614; JP 2015096460 A 20150511; KR 20147034629 A 20130614; KR 20167003252 A 20130614